



RD Number: RD180

RD Title: TB67B000AFG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	IC1	1	TB67B000AFG	TB67B000AFG	TOSHIBA	Brushless Motor Driver	HSSOP34	
2	R1	1	68k Ω	—	—	Chip resistor		
3	R1A	0	Not mount	—	—			✓
4	R2	1	Lead jumper	—	—	Short with jumper wire		
5	R3	1	0.51 Ω	—	—	Resistor		
6	R3A	0	Not mount	—	—			✓
7	R4	0	Not mount	—	—			✓
8	R5	0	Not mount	—	—			✓
9	R6	0	Not mount	—	—			✓
10	R7	0	Not mount	—	—			✓
11	R8	0	Not mount	—	—			✓
12	R9	0	Not mount	—	—			✓
13	R10	0	Not mount	—	—			✓
14	R11	0	Not mount	—	—			✓
15	R12	0	Not mount	—	—			✓
16	R13	0	Not mount	—	—			✓
17	C1	1	0.01 μ F	—	—	Chip capacitor		
18	C2	1	0.1 μ F	—	—	Capacitor		
19	C3	1	1 μ F 50V	—	—	Capacitor		
20	C4	1	0.001 μ F	—	—	Capacitor		
21	C5	0	Not mount	—	—			✓
22	C6	1	10 μ F 50V	—	—	Capacitor		
23	C7	1	0.1 μ F	—	—	Capacitor		
24	C8	1	2.2 μ F 50V	—	—	Capacitor		
25	C9	1	2.2 μ F 50V	—	—	Capacitor		
26	C10	1	2.2 μ F 50V	—	—	Capacitor		
27	C11	1	0.1 μ F	—	—	Capacitor		
28	C12	1	0.1 μ F	—	—	Capacitor		
29	C13	1	0.1 μ F	—	—	Capacitor		
30	C14	0	Not mount	—	—			✓
31	C15	0	Not mount	—	—			✓
32	C16	0	Not mount	—	—			✓
33	C17	0	Not mount	—	—			✓
34	C18	1	0.1 μ F	—	—	Chip capacitor		

35	C19	0	Not mount	-	-		✓
36	C20	0	Not mount	-	-		✓
37	C21	0	Not mount	-	-		✓
38	C22	0	Not mount	-	-		✓
39	SW1	1	Toggle switch	-	-	Toggle switch	
40	SW2	1	Toggle switch	-	-	Toggle switch	
41	SW3	1	Toggle switch	-	-	Toggle switch	
42	JP1	0	Not mount	-	-		✓
43	JP2	0	Not mount	-	-		✓
44	JP3	0	Not mount	-	-		✓
45	JP4	0	Not mount	-	-		✓
46	JP5	2	Short with solder	-	-	Short slit land with solder	
47	JP6	2	Short with solder	-	-	Short slit land with solder	
48	JP7	2	Short with solder	-	-	Short slit land with solder	
49	JP8	0	Not mount	-	-		✓
50	JP9	0	Not mount	-	-		✓
51	JP10	0	Not mount	-	-		✓
52	JP11	0	Not mount	-	-		✓
53	JP12	0	Not mount	-	-		✓
54	JP13	0	Not mount	-	-		✓
55	JP14	0	Not mount	-	-		✓
56	JP15	0	Not mount	-	-		✓
57	JP16	0	Not mount	-	-		✓
58	JP17	3	Short with solder	-	-	Short slit land with solder	
59	JP19	3	Short with solder	-	-	Short slit land with solder	
60	U	1	Check terminal	-	-	Metal post	
61	V	1	Check terminal	-	-	Metal post	
62	W	1	Check terminal	-	-	Metal post	
63	VBB	1	Check terminal	-	-	Metal post	
64	PGND1	1	Check terminal	-	-	Metal post	
65	VCC	1	Check terminal	-	-	Metal post	
66	SGND1	1	Check terminal	-	-	Metal post	
67	FG	1	Check terminal	-	-	Metal post	
68	VSP	1	Check terminal	-	-	Metal post	
69	LA	1	Check terminal	-	-	Metal post	
70	SGND2	1	Check terminal	-	-	Metal post	
71	HU	1	Check terminal	-	-	Metal post	
72	HV	1	Check terminal	-	-	Metal post	
73	HW	1	Check terminal	-	-	Metal post	
74	VREFOUT2	1	Check terminal	-	-	Metal post	
75	SGND3	1	Check terminal	-	-	Metal post	
76	HUP	1	Check terminal	-	-	Metal post	
77	HUM	1	Check terminal	-	-	Metal post	

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